



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	02/25/2015
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	Group MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNPP*F62G81B	A	ZA41	02/25/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
340.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
AXL	5X7.5X2.37	N/A	Through-hole	
Comment	Package: DO 41 PLASTIC; MD valid for STTH1L06			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

ELV exemption number	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Exemption Id.	Description
	#N/A
	#N/A

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNPP*F6ZG81B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.839	mg	supplier	die	Silicon (Si)	7440-21-3		0.789	mg	940405	2321
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	5959	15
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1192	3
				supplier	metallization	Nickel (Ni)	7440-02-0		0.004	mg	4768	12
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	4768	12
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.005	mg	5959	15
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.003	mg	3576	9
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1192	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	5959	15
				supplier	polymer die coating	Durimide	proprietary		0.022	mg	26222	65
Leadframe	Copper & its alloys	249.081	mg	supplier	Frame Alloy	Cu	7440-50-8		248.956	mg	999498	732224
				supplier	Frame Alloy	Zn	7440-66-6		0.010	mg	40	29
				supplier	Frame Alloy	Fe	7439-89-6		0.025	mg	100	74
				supplier	Frame Alloy	Iron Phosphide (Fe2P)	1310-43-6		0.090	mg	361	265
Die attach	Other Organic Materials	2.200	mg	supplier	JIG R	Pb	7439-92-1	7a-Lead in high me	2.035	mg	925000	5985
				supplier	soft solder	Sn	7440-31-5		0.055	mg	25000	162
				supplier	soft solder	Ag	7440-22-4		0.110	mg	50000	324
Encapsulation	Other inorganic materials	84.401	mg	supplier	Moulding Compound	Silica fused(SiO2)	7631-86-9		30.387	mg	360031	89374
				supplier	Moulding Compound	silica quartz	14808-60-7		48.950	mg	579969	143971
				supplier	Moulding Compound	phenolic resin	9003-35-4		4.220	mg	49999	12412
				supplier	Moulding Compound	carbon black	1333-86-4		0.844	mg	10000	2482
Finishing	Other inorganic materials	3.479	mg	supplier	Connection Coating	Sn	7440-31-5		3.479	mg	1000000	10232